Data sheet acquired from Harris Semiconductor SCHS133C

August 1997 - Revised May 2003

High-Speed CMOS Logic BCD-to-Decimal Decoders (1 of 10)

Features

- · Buffered Inputs and Outputs
- Typical Propagation Delay: 12ns at V_{CC} = 5V, C_L = 15pF, T_A = 25°C
- Fanout (Over Temperature Range)
- Wide Operating Temperature Range . . . -55°C to 125°C
- Balanced Propagation Delay and Transition Times
- Significant Power Reduction Compared to LSTTL Logic ICs
- HC Types
 - 2V to 6V Operation
 - High Noise Immunity: N_{IL} = 30%, N_{IH} = 30% of V_{CC} at V_{CC} = 5V
- HCT Types
 - 4.5V to 5.5V Operation
 - Direct LSTTL Input Logic Compatibility,
 V_{IL}= 0.8V (Max), V_{IH} = 2V (Min)
 - CMOS Input Compatibility, $I_I \le 1 \mu A$ at V_{OL} , V_{OH}

Description

The 'HC42 and CD74HCT42 BCD-to-Decimal Decoders utilize silicon-gate CMOS technology to achieve operating speeds similar to LSTTL decoders with the low power consumption of standard CMOS integrated circuits. These devices have the capability of driving 10 LSTLL loads and are compatible with the standard LS logic family. One of ten outputs (low on select) is selected in accordance with the BCD input. Non-valid BCD inputs result in none of the outputs being selected (all outputs are high).

Ordering Information

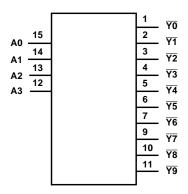
PART NUMBER	TEMP. RANGE (°C)	PACKAGE
CD54HC42F3A	-55 to 125	16 Ld CERDIP
CD74HC42E	-55 to 125	16 Ld PDIP
CD74HC42M	-55 to 125	16 Ld SOIC
CD74HCT42E	-55 to 125	16 Ld PDIP

Pinout

(CERDIP) **CD74HC42** (PDIP, SOIC) CD74HCT42 (PDIP) **TOP VIEW** Y0 1 16 V_{CC} **Y1** 2 15 A0 Y2 3 14 A1 Y3 4 13 A2 Y4 5 12 A3 **Y5** 6 11 Y9 10 Y8 Y6 7 9 Y7 GND 8

CD54HC42

Functional Diagram



TRUTH TABLE

	INP	UTS						OUT	PUTS				
А3	A2	A1	A0	Y0	<u>Y1</u>	<u> 72</u>	<u> 73</u>	<u>¥4</u>	<u>Y5</u>	<u>Y6</u>	<u>77</u>	<u>78</u>	<u> 79</u>
L	L	L	L	L	Н	Н	Н	Н	Н	Н	Н	Н	Н
L	L	L	Н	Н	L	Н	Н	Н	Н	Н	Н	Н	Н
L	L	Н	L	Н	Н	L	Н	Н	Н	Н	Н	Н	Н
L	L	Н	Н	Н	Н	Н	L	Н	Н	Н	Н	Н	Н
L	Н	L	L	Н	Н	Н	Н	L	Н	Н	Н	Н	Н
L	Н	L	Н	Н	Н	Н	Н	Н	L	Н	Н	Н	Н
L	Н	Н	L	Н	Н	Н	Н	Н	Н	L	Н	Н	Н
L	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	L	Н	Н
Н	L	L	L	Н	Н	Н	Н	Н	Н	Н	Н	L	Н
Н	L	L	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	L
Н	L	Н	L	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н
Н	L	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н
Н	Н	L	L	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н
Н	Н	L	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н
Н	Н	Н	L	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н
Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н

H = High Voltage Level, L = Low Voltage Level

Absolute Maximum Ratings

Thermal Information

Thermal Resistance (Typical, Note 1)	θ_{JA} (°C/W)
E (PDIP) Package	. 67
M (SOIC) Package	
Maximum Junction Temperature	
Maximum Storage Temperature Range	-65°C to 150°C
Maximum Lead Temperature (Soldering 10s)	300°C
(SOIC - Lead Tips Only)	

Operating Conditions

Temperature Range (T _A)55°C to 125°C
Supply Voltage Range, V _{CC}
HC Types2V to 6V
HCT Types
DC Input or Output Voltage, V _I , V _O 0V to V _{CC}
Input Rise and Fall Time
2V
4.5V 500ns (Max)
6V

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

1. The package thermal impedance is calculated in accordance with JESD 51-7.

DC Electrical Specifications

		TE: CONDI				25°C		-40°C 1	O 85°C	-55°C TO 125°C		
PARAMETER	SYMBOL	V _I (V)	I _O (mA)	(S)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNITS
HC TYPES							-	-				
High Level Input	V _{IH}	-	-	2	1.5	-	-	1.5	-	1.5	-	V
Voltage				4.5	3.15	•	-	3.15	-	3.15	-	V
				6	4.2	-	-	4.2	-	4.2	-	V
Low Level Input	V _{IL}	-	-	2	-	-	0.5	-	0.5	-	0.5	V
Voltage				4.5	-	-	1.35	-	1.35	-	1.35	V
				6	-	-	1.8	-	1.8	-	1.8	V
High Level Output	VoH	V _{IH} or V _{IL}	-0.02	2	1.9	-	-	1.9	-	1.9	-	V
Voltage CMOS Loads			-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
OWIGO Educa			-0.02	6	5.9	-	-	5.9	-	5.9	-	V
High Level Output	7		-	-	-	-	-	-	-	-	-	V
Voltage TTL Loads			-4	4.5	3.98	-	-	3.84	-	3.7	-	V
TTE LOGUS			-5.2	6	5.48	-	-	5.34	-	5.2	-	V
Low Level Output	V _{OL}	V _{IH} or V _{IL}	0.02	2	-	-	0.1	-	0.1	-	0.1	V
Voltage CMOS Loads			0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
OWOO LOAGS			0.02	6	-	-	0.1	-	0.1	-	0.1	V
Low Level Output	7		-	-	-	-	-	-	-	-	-	V
Voltage TTL Loads			4	4.5	-	-	0.26	-	0.33	-	0.4	V
I I L Loads			5.2	6	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	IĮ	V _{CC} or GND	-	6	-	-	±0.1	-	±1	-	±1	μΑ
Quiescent Device Current	lcc	V _{CC} or GND	0	6	-	-	8	-	80	-	160	μА

DC Electrical Specifications (Continued)

		TES CONDI		V _{CC}	25°C		-40°C T	O 85°C	-55°C T	O 125°C		
PARAMETER	SYMBOL	V _I (V)	I _O (mA)	(V)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNITS
HCT TYPES	HCT TYPES											
High Level Input Voltage	V _{IH}	-	-	4.5 to 5.5	2	-	-	2	-	2	-	V
Low Level Input Voltage	V _{IL}	-	-	4.5 to 5.5	-	-	0.8	-	0.8	-	0.8	V
High Level Output Voltage CMOS Loads	V _{OH}	V _{IH} or V _{IL}	-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
High Level Output Voltage TTL Loads			-4	4.5	3.98	-	-	3.84	-	3.7	-	V
Low Level Output Voltage CMOS Loads	V _{OL}	V _{IH} or V _{IL}	0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
Low Level Output Voltage TTL Loads			4	4.5	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	lı	V _{CC} and GND	0	5.5	-		±0.1	-	±1	-	±1	μА
Quiescent Device Current	Icc	V _{CC} or GND	0	5.5	-	-	8	-	80	-	160	μА
Additional Quiescent Device Current Per Input Pin: 1 Unit Load	ΔI _{CC} (Note 2)	V _{CC} -2.1	-	4.5 to 5.5	-	100	360	-	450	-	490	μА

NOTE:

HCT Input Loading Table

INPUT	UNIT LOADS
All	1

NOTE: Unit Load is ΔI_{CC} limit specified in DC Electrical Table, e.g. 360µA max at 25 $^{\!0}C.$

Switching Specifications Input t_r , t_f = 6ns

		TEST			25°C		-40 ⁰ 85	С ТО °С		C TO 5°C	
PARAMETER	SYMBOL	CONDITIONS	V _{CC} (V)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNITS
HC TYPES			-		-	_	_	_		-	
Propagation Delay,	t _{PLH} , t _{PHL}	C _L = 50pF	2	-	-	150	-	190	-	225	ns
Input to Y (Figure 1)			4.5	-	-	30	-	38	-	45	ns
			6	-	-	26	-	33	-	38	ns
Any Input to \overline{Y}	t _{PLH} , t _{PHL}	C _L = 15pF	5	-	12	-	-	-	-	-	ns
Output Transition Time	t _{TLH} , t _{THL}	C _L = 50pF	2	-	-	75	-	95	-	110	ns
(Figure 1)			4.5	-	-	15	-	19	-	22	ns
			6	-	-	13	-	16	-	19	ns
Input Capacitance	C _{IN}	-	-	-	_	10	_	10	-	10	pF

^{2.} For dual-supply systems theoretical worst case ($V_I = 2.4V$, $V_{CC} = 5.5V$) specification is 1.8mA.

Switching Specifications Input t_f , $t_f = 6ns$ (Continued)

		TEST			25°C			С ТО °С		C TO 5°C	
PARAMETER	SYMBOL	CONDITIONS	V _{CC} (V)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNITS
Power Dissipation Capacitance (Notes 3, 4)	C _{PD}	-	5	-	65	-	-	-	-	-	pF
HCT TYPES											
Propagation Delay, Input to Y (Figure 2)	t _{PLH} , t _{PHL}	C _L = 50pF	4.5	-	-	35	-	44	-	53	ns
Any Input to Y	t _{PLH} , t _{PHL}	C _L = 15pF	5	-	14	-	-	-	-	-	ns
Output Transition Time (Figure 2)	t _{TLH} , t _{THL}	C _L = 50pF	4.5	-	-	15	-	19	-	22	ns
Input Capacitance	C _{IN}	-	-	-	-	10	-	10	-	10	pF
Power Dissipation Capacitance (Notes 3, 4)	C _{PD}	-	5	-	70	-	-	-	-	-	pF

NOTES:

- 3. $\ensuremath{C_{PD}}$ is used to determine the dynamic power consumption, per package.
- 4. $P_D = V_{CC}^2 f_i (C_{PD} + C_L)$ where: $f_i = Input$ Frequency, $C_L = Output$ Load Capacitance, $V_{CC} = Supply$ Voltage.

Test Circuits and Waveforms

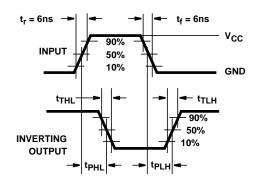


FIGURE 1. HC AND HCU TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC

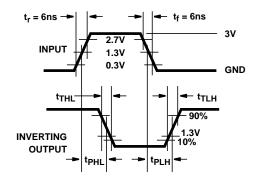


FIGURE 2. HCT TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC





i.com 28-Feb-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
CD54HC42F3A	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
CD74HC42E	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
CD74HC42M	ACTIVE	SOIC	D	16	40	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD74HCT42E	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

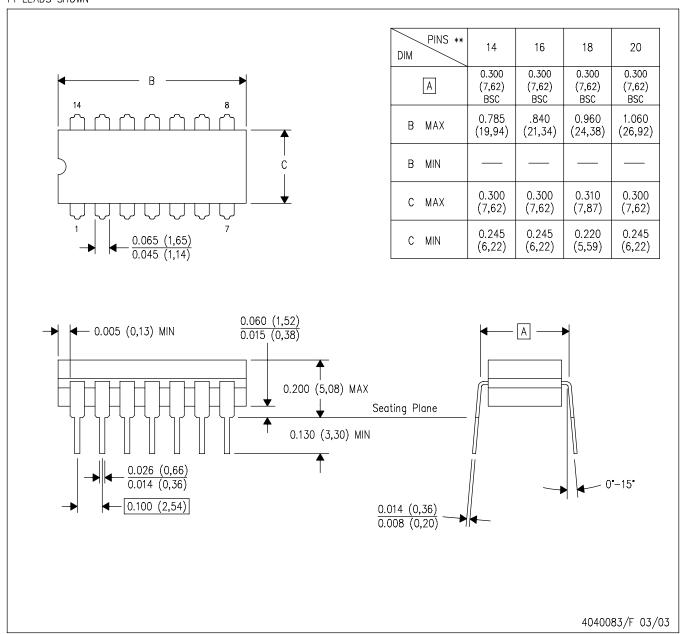
Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

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14 LEADS SHOWN



NOTES:

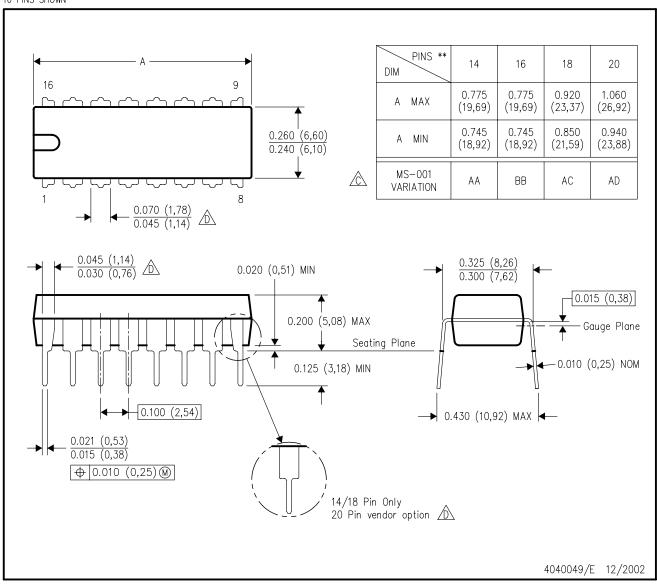
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

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N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

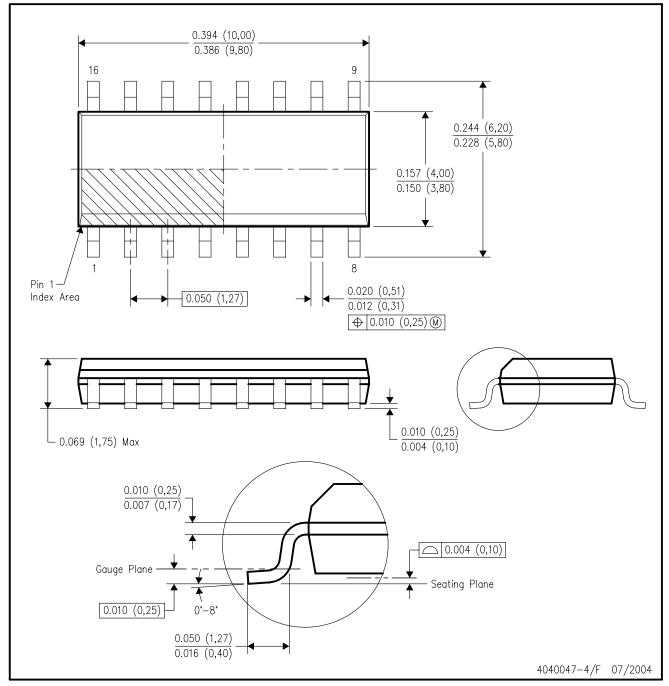


NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AC.

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